

Title (en)
METHOD FOR LOCAL ETCHING OF THE SURFACE OF A SUBSTRATE

Title (de)
VERFAHREN ZUR LOKALEN ÄTZUNG DER OBERFLÄCHE EINES SUBSTRATS

Title (fr)
PROCEDE DE GRAVURE LOCALISEE DE LA SURFACE D'UN SUBSTRAT

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Application
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Abstract (en)
[origin: WO2009103907A2] The invention relates to a method for the local etching of the surface of a substrate, characterised in that it comprises:
a) making a gas-pervious polymer pad that comprises three-dimensional patterns on one surface thereof; b) contacting the surface including the pad patterns with the substrate; c) submitting the pad/substrate assembly to a plasma so that the species present in the plasma are accelerated and diffused through the pad until they reach the substrate.

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